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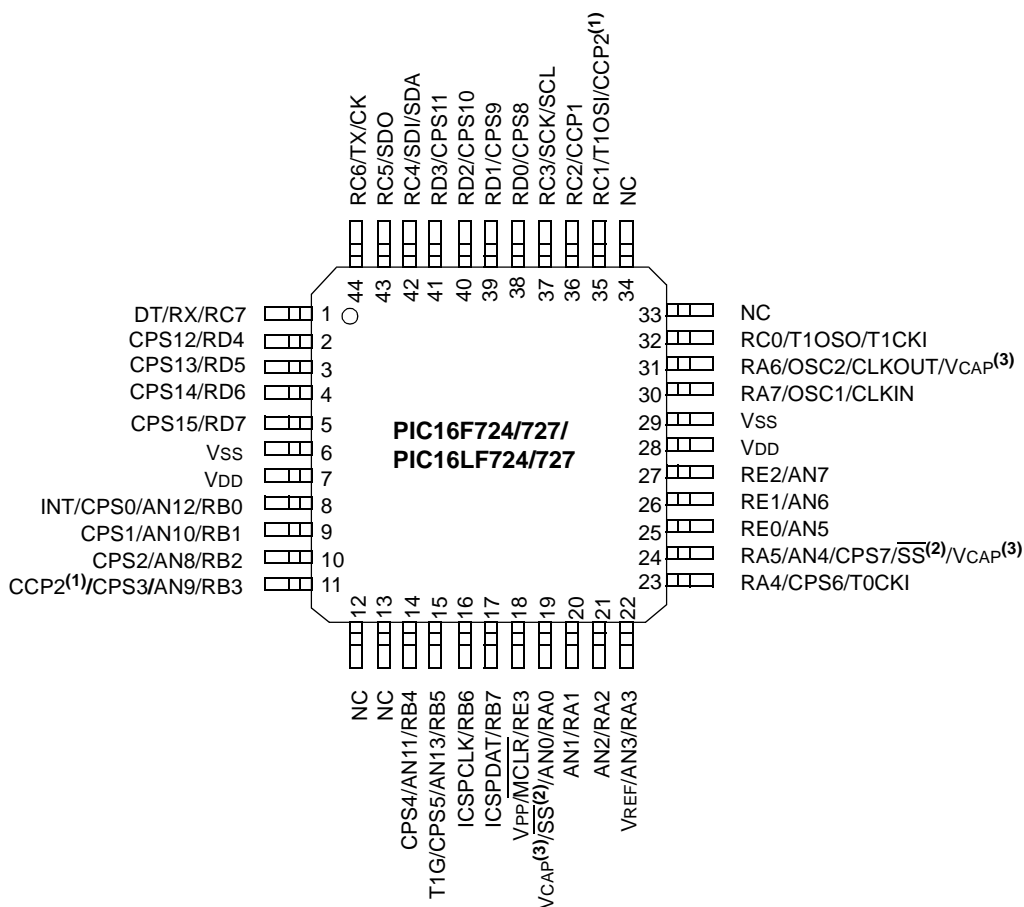
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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f724t-i-pt

PIC16(L)F722/3/4/6/7

Pin Diagrams – 44-PIN TQFP (PIC16F724/727/PIC16LF724/727)



Note 1: CCP2 pin location may be selected as RB3 or RC1.

2: SS pin location may be selected as RA5 or RA0.

3: PIC16F724/727 devices only.

PIC16(L)F722/3/4/6/7

TABLE 1-1: PIC16(L)F722/3/4/6/7 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/ \overline{SS} /VCAP	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel 0 input.
	\overline{SS}	ST	—	Slave Select input.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F72X only).
RA1/AN1	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel 1 input.
RA2/AN2	RA2	TTL	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel 2 input.
RA3/AN3/VREF	RA3	TTL	CMOS	General purpose I/O.
	AN3	AN	—	A/D Channel 3 input.
	VREF	AN	—	A/D Voltage Reference input.
RA4/CPS6/T0CKI	RA4	TTL	CMOS	General purpose I/O.
	CPS6	AN	—	Capacitive sensing input 6.
	T0CKI	ST	—	Timer0 clock input.
RA5/AN4/CPS7/ \overline{SS} /VCAP	RA5	TTL	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	CPS7	AN	—	Capacitive sensing input 7.
	\overline{SS}	ST	—	Slave Select input.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F72X only).
RA6/OSC2/CLKOUT/VCAP	RA6	TTL	CMOS	General purpose I/O.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	Fosc/4 output.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F72X only).
RA7/OSC1/CLKIN	RA7	TTL	CMOS	General purpose I/O.
	OSC1	XTAL	—	Crystal/Resonator (LP, XT, HS modes).
	CLKIN	CMOS	—	External clock input (EC mode).
	CLKIN	ST	—	RC oscillator connection (RC mode).
RB0/AN12/CPS0/INT	RB0	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN12	AN	—	A/D Channel 12 input.
	CPS0	AN	—	Capacitive sensing input 0.
	INT	ST	—	External interrupt.
RB1/AN10/CPS1	RB1	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN10	AN	—	A/D Channel 10 input.
	CPS1	AN	—	Capacitive sensing input 1.
RB2/AN8/CPS2	RB2	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN8	AN	—	A/D Channel 8 input.
	CPS2	AN	—	Capacitive sensing input 2.
RB3/AN9/CPS3/CCP2	RB3	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN9	AN	—	A/D Channel 9 input.
	CPS3	AN	—	Capacitive sensing input 3.
	CCP2	ST	CMOS	Capture/Compare/PWM2.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I²C = Schmitt Trigger input with I²C
HV = High Voltage XTAL = Crystal levels

PIC16(L)F722/3/4/6/7

REGISTER 4-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TOIE	INTE	RBIE ⁽¹⁾	T0IF ⁽²⁾	INTF	RBIF
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts
- bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
- bit 5 **TOIE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt
- bit 4 **INTE:** RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt
- bit 3 **RBIE:** PORTB Change Interrupt Enable bit⁽¹⁾
1 = Enables the PORTB change interrupt
0 = Disables the PORTB change interrupt
- bit 2 **T0IF:** Timer0 Overflow Interrupt Flag bit⁽²⁾
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow
- bit 1 **INTF:** RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur
- bit 0 **RBIF:** PORTB Change Interrupt Flag bit
1 = When at least one of the PORTB general purpose I/O pins changed state (must be cleared in software)
0 = None of the PORTB general purpose I/O pins have changed state

Note 1: The appropriate bits in the IOCB register must also be set.

2: T0IF bit is set when Timer0 rolls over. Timer0 is unchanged on Reset and should be initialized before clearing T0IF bit.

[illegible]

6.5.6 RD4/CPS12

Figure 6-21 shows the diagram for these pins. They are configurable to function as one of the following:

- a general purpose I/O
- a capacitive sensing input

6.5.7 RD5/CPS13

Figure 6-21 shows the diagram for these pins. They are configurable to function as one of the following:

- a general purpose I/O
- a capacitive sensing input

6.5.8 RD6/CPS14

Figure 6-21 shows the diagram for these pins. They are configurable to function as one of the following:

- a general purpose I/O
- a capacitive sensing input

6.5.9 RD7/CPS15

Figure 6-21 shows the diagram for these pins. They are configurable to function as one of the following:

- a general purpose I/O
- a capacitive sensing input

FIGURE 6-21: BLOCK DIAGRAM OF RD<7:0>

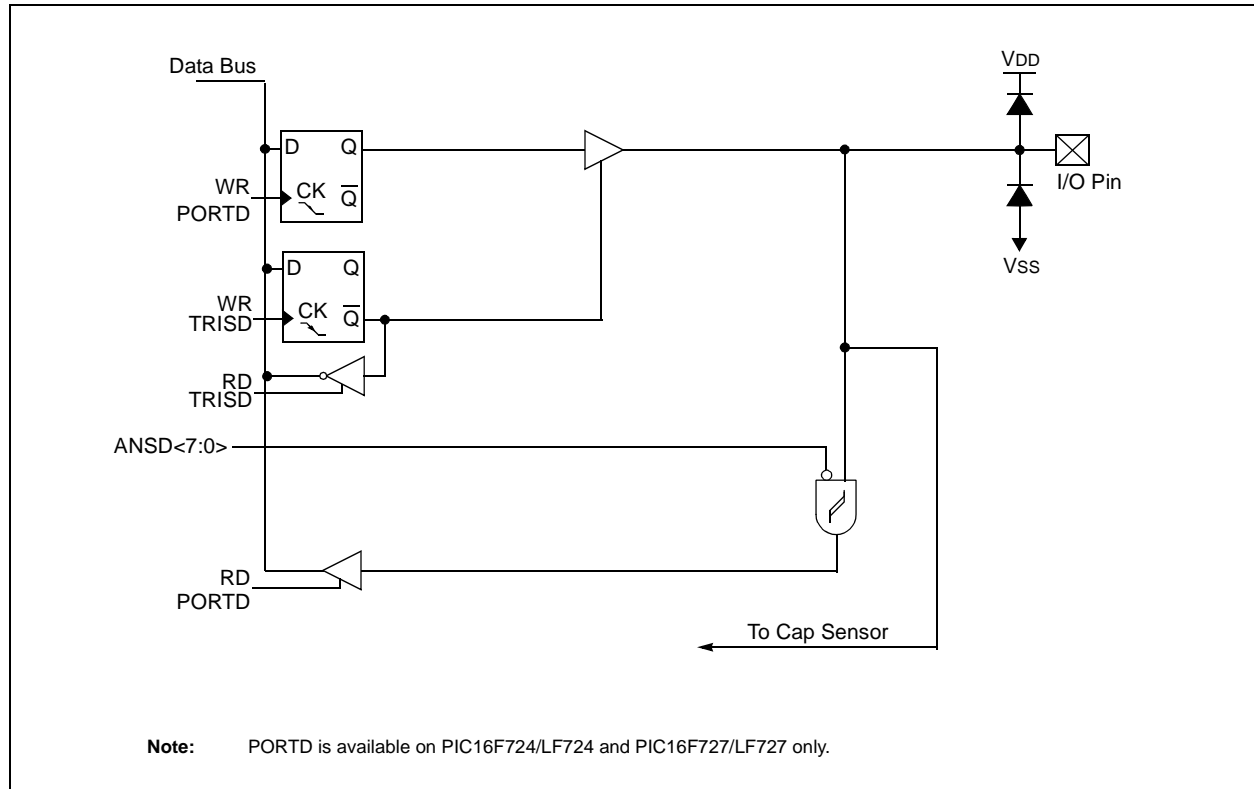


TABLE 6-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD⁽¹⁾

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ANSELD	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
CPSCON0	CPSON	—	—	—	CPSRNG1	CPSRNG0	CPSOUT	T0XCS	0--- 0000	0--- 0000
CPSCON1	—	—	—	—	CPSCH3	CPSCH2	CPSCH1	CPSCH0	---- 0000	---- 0000
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	xxxx xxxx
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by PORTD.

Note 1: These registers are not implemented on the PIC16F722/723/726/PIC16LF722/723/726 devices, read as '0'.

7.6 External Clock Modes

7.6.1 OSCILLATOR START-UP TIMER (OST)

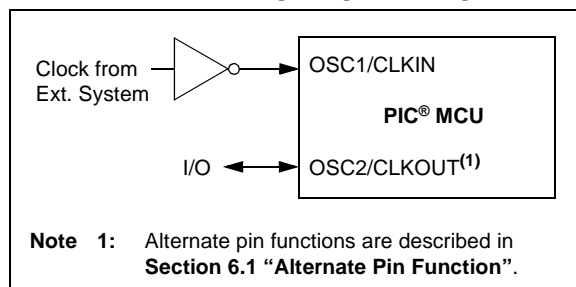
If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations on the OSC1 pin before the device is released from Reset. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

7.6.2 EC MODE

The External Clock (EC) mode allows an externally generated logic level as the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input and the OSC2 is available for general purpose I/O. Figure 7-2 shows the pin connections for EC mode.

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 7-2: EXTERNAL CLOCK (EC) MODE OPERATION



7.6.3 LP, XT, HS MODES

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 7-3). The mode selects a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

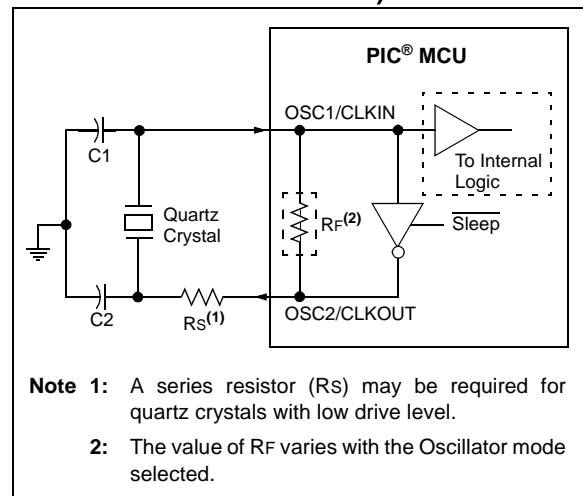
LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is best suited to drive resonators with a low drive level specification, for example, tuning fork type crystals.

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 7-3 and Figure 7-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

FIGURE 7-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, *Crystal Oscillator Basics and Crystal Selection for $rPIC^{\circ}$ and PIC° Devices* (DS00826)
- AN849, *Basic PIC° Oscillator Design* (DS00849)
- AN943, *Practical PIC° Oscillator Analysis and Design* (DS00943)
- AN949, *Making Your Oscillator Work* (DS00949).

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9.2.6 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
 - Disable pin output driver (Refer to the TRIS register)
 - Configure pin as analog (Refer to the ANSEL register)
2. Configure the ADC module:
 - Select ADC conversion clock
 - Configure voltage reference
 - Select ADC input channel
 - Turn on ADC module
3. Configure ADC interrupt (optional):
 - Clear ADC interrupt flag
 - Enable ADC interrupt
 - Enable peripheral interrupt
 - Enable global interrupt⁽¹⁾
4. Wait the required acquisition time⁽²⁾.
5. Start conversion by setting the GO/DONE bit.
6. Wait for ADC conversion to complete by one of the following:
 - Polling the GO/DONE bit
 - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 9.3 “A/D Acquisition Requirements”**.

EXAMPLE 9-1: A/D CONVERSION

```
;This code block configures the ADC
;for polling, Vdd reference, Frc clock
;and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL    ADCON1    ;
MOVLW      B'01110000' ;ADC Frc clock,
                                ;VDD reference
MOVWF      ADCON1    ;
BANKSEL    TRISA     ;
BSF        TRISA,0    ;Set RA0 to input
BANKSEL    ANSELA    ;
BSF        ANSELA,0   ;Set RA0 to analog
BANKSEL    ADCON0    ;
MOVLW      B'00000001' ;AN0, On
MOVWF      ADCON0    ;
CALL       SampleTime ;Acquisiton delay
BSF        ADCON0,GO  ;Start conversion
BTFSC      ADCON0,GO  ;Is conversion done?
GOTO       $-1        ;No, test again
BANKSEL    ADRES      ;
MOVF       ADRES,W    ;Read result
MOVWF      RESULT     ;store in GPR space
```

REGISTER 11-1: OPTION_REG: OPTION REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBP}}\text{U}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 7 **$\overline{\text{RBP}}\text{U}$** : PORTB Pull-up Enable bit
 1 = PORTB pull-ups are disabled
 0 = PORTB pull-ups are enabled by individual port latch values
- bit 6 **INTEDG**: Interrupt Edge Select bit
 1 = Interrupt on rising edge of INT pin
 0 = Interrupt on falling edge of INT pin
- bit 5 **T0CS**: TMR0 Clock Source Select bit
 1 = Transition on T0CKI pin or CPSOSC signal
 0 = Internal instruction cycle clock (Fosc/4)
- bit 4 **T0SE**: TMR0 Source Edge Select bit
 1 = Increment on high-to-low transition on T0CKI pin
 0 = Increment on low-to-high transition on T0CKI pin
- bit 3 **PSA**: Prescaler Assignment bit
 1 = Prescaler is assigned to the WDT
 0 = Prescaler is assigned to the Timer0 module
- bit 2-0 **PS<2:0>**: Prescaler Rate Select bits

BIT VALUE	TMR0 RATE	WDT RATE
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

TABLE 11-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER0

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
CPSCON0	CPSON	—	—	—	CPSRNG1	CPSRNG0	CPSOUT	T0XCS	0--- 0000	0--- 0000
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
OPTION_REG	$\overline{\text{RBP}}\text{U}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
TMR0	Timer0 Module Register								xxxx xxxx	uuuu uuuu
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Timer0 module.

TABLE 15-4: SUMMARY OF REGISTERS ASSOCIATED WITH COMPARE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	--00 0000	--00 0000
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
CCPRxL	Capture/Compare/PWM Register X Low Byte								xxxx xxxx	uuuu uuuu
CCPRxH	Capture/Compare/PWM Register X High Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIE2	—	—	—	—	—	—	—	CCP2IE	---- --0	---- --0
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIR2	—	—	—	—	—	—	—	CCP2IF	---- --0	---- --0
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	—	TMR1ON	0000 00-0	uuuu uu-u
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GSS1	T1GSS0	0000 0x00	0000 0x00
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: — = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Compare.

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REGISTER 16-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit⁽¹⁾

1 = Serial port enabled (configures RX/DT and TX/CK pins as serial port pins)

0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-bit Receive Enable bit

1 = Selects 9-bit reception

0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit

Asynchronous mode:

Don't care

Synchronous mode – Master:

1 = Enables single receive

0 = Disables single receive

This bit is cleared after reception is complete.

Synchronous mode – Slave:

Don't care

bit 4 **CREN:** Continuous Receive Enable bit

Asynchronous mode:

1 = Enables receiver

0 = Disables receiver

Synchronous mode:

1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)

0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit

Asynchronous mode 9-bit (RX9 = 1):

1 = Enables address detection, enable interrupt and load the receive buffer when RSR<8> is set

0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit

Asynchronous mode 8-bit (RX9 = 0):

Don't care

Synchronous mode:

Must be set to '0'

bit 2 **FERR:** Framing Error bit

1 = Framing error (can be updated by reading RCREG register and receive next valid byte)

0 = No framing error

bit 1 **OERR:** Overrun Error bit

1 = Overrun error (can be cleared by clearing bit CREN)

0 = No overrun error

bit 0 **RX9D:** Ninth bit of Received Data

This can be address/data bit or a parity bit and must be calculated by user firmware.

Note 1: The AUSART module automatically changes the pin from tri-state to drive as needed. Configure TRISx = 1.

17.1.1 MASTER MODE

In Master mode, data transfer can be initiated at any time because the master controls the SCK line. Master mode determines when the slave (Figure 17-1, Processor 2) transmits data via control of the SCK line.

17.1.1.1 Master Mode Operation

The SSP consists of a transmit/receive shift register (SSPSR) and a buffer register (SSPBUF). The SSPSR register shifts the data in and out of the device, MSb first. The SSPBUF register holds the data that is written out of the master until the received data is ready. Once the eight bits of data have been received, the byte is moved to the SSPBUF register. The Buffer Full Status bit, BF of the SSPSTAT register, and the SSP Interrupt Flag bit, SSPIF of the PIR1 register, are then set.

Any write to the SSPBUF register during transmission/reception of data will be ignored and the Write Collision Detect bit, WCOL of the SSPCON register, will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully.

When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data is written to the SSPBUF. The BF bit of the SSPSTAT register is set when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, the BF bit is cleared. This data may be irrelevant if the SPI is only a transmitter. The SSP interrupt may be used to determine when the transmission/reception is complete and the SSPBUF must be read and/or written. If interrupts are not used, then software polling can be done to ensure that a write collision does not occur. Example 17-1 shows the loading of the SSPBUF (SSPSR) for data transmission.

Note: The SSPSR is not directly readable or writable and can only be accessed by addressing the SSPBUF register.

17.1.1.2 Enabling Master I/O

To enable the serial port, the SSPEN bit of the SSPCON register, must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, re-initialize the SSPCON register and then set the SSPEN bit. If a Master mode of operation is selected in the SSPM bits of the SSPCON register, the SDI, SDO and SCK pins will be assigned as serial port pins.

For these pins to function as serial port pins, they must have their corresponding data direction bits set or cleared in the associated TRIS register as follows:

- SDI configured as input
- SDO configured as output
- SCK configured as output

17.1.1.3 Master Mode Setup

In Master mode, the data is transmitted/received as soon as the SSPBUF register is loaded with a byte value. If the master is only going to receive, SDO output could be disabled (programmed and used as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate.

When initializing SPI Master mode operation, several options need to be specified. This is accomplished by programming the appropriate control bits in the SSPCON and SSPSTAT registers. These control bits allow the following to be specified:

- SCK as clock output
- Idle state of SCK (CKP bit)
- Data input sample phase (SMP bit)
- Output data on rising/falling edge of SCK (CKE bit)
- Clock bit rate

In Master mode, the SPI clock rate (bit rate) is user selectable to be one of the following:

- $F_{osc}/4$ (or TCY)
- $F_{osc}/16$ (or $4 \cdot TCY$)
- $F_{osc}/64$ (or $16 \cdot TCY$)
- (Timer2 output)/2

This allows a maximum data rate of 5 Mbps (at $F_{osc} = 20$ MHz).

Figure 17-3 shows the waveforms for Master mode. The clock polarity is selected by appropriately programming the CKP bit of the SSPCON register. When the CKE bit is set, the SDO data is valid before there is a clock edge on SCK. The sample time of the input data is shown based on the state of the SMP bit and can occur at the middle or end of the data output time. The time when the SSPBUF is loaded with the received data is shown.

17.1.1.4 Sleep in Master Mode

In Master mode, all module clocks are halted and the transmission/reception will remain in their current state, paused, until the device wakes from Sleep. After the device wakes up from Sleep, the module will continue to transmit/receive data.

21.0 INSTRUCTION SET SUMMARY

The PIC16(L)F722/3/4/6/7 instruction set is highly orthogonal and is comprised of three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

Each PIC16 instruction is a 14-bit word divided into an **opcode**, which specifies the instruction type and one or more **operands**, which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 21-1, while the various opcode fields are summarized in Table 21-1.

Table 21-2 lists the instructions recognized by the MPASM™ assembler.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator, which selects the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8-bit or 11-bit constant, or literal value.

One instruction cycle consists of four oscillator periods; for an oscillator frequency of 4 MHz, this gives a nominal instruction execution time of 1 μs. All instructions are executed within a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of an instruction. When this occurs, the execution takes two instruction cycles, with the second cycle executed as a NOP.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

21.1 Read-Modify-Write Operations

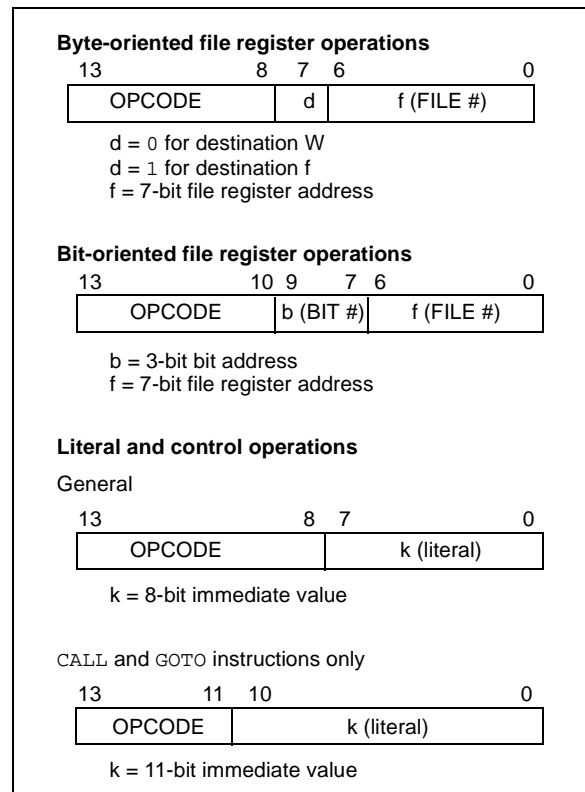
Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register.

For example, a `CLRF PORTB` instruction will read PORTB, clear all the data bits, then write the result back to PORTB. This example would have the unintended consequence of clearing the condition that set the RBIF flag.

TABLE 21-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1.
PC	Program Counter
TO	Time-out bit
C	Carry bit
DC	Digit carry bit
Z	Zero bit
PD	Power-down bit

FIGURE 21-1: GENERAL FORMAT FOR INSTRUCTIONS



PIC16(L)F722/3/4/6/7

23.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings^(†)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS, PIC16F72X	-0.3V to +6.5V
Voltage on VCAP pin with respect to VSS, PIC16F72X	-0.3V to +4.0V
Voltage on VDD with respect to VSS, PIC16LF72X	-0.3V to +4.0V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS	-0.3V to +9.0V
Voltage on all other pins with respect to VSS	-0.3V to (VDD + 0.3V)
Total power dissipation ⁽¹⁾	800 mW
Maximum current out of VSS pin	95 mA
Maximum current into VDD pin	70 mA
Clamp current, I _K (V _{PIN} < 0 or V _{PIN} > VDD).....	± 20 mA
Maximum output current sunk by any I/O pin.....	25 mA
Maximum output current sourced by any I/O pin.....	25 mA
Maximum current sunk by all ports ⁽²⁾ , -40°C ≤ T _A ≤ +85°C for industrial	200 mA
Maximum current sunk by all ports ⁽²⁾ , -40°C ≤ T _A ≤ +125°C for extended	90 mA
Maximum current sourced by all ports ⁽²⁾ , 40°C ≤ T _A ≤ +85°C for industrial	140 mA
Maximum current sourced by all ports ⁽²⁾ , -40°C ≤ T _A ≤ +125°C for extended.....	65 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

23.2 DC Characteristics: PIC16(L)F722/3/4/6/7-I/E (Industrial, Extended)

PIC16LF722/3/4/6/7			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722/3/4/6/7			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						VDD	Note
	Supply Current (IDD) ^(1, 2)						
D009	LDO Regulator	—	350	—	μA	—	HS, EC OR INTOSC/INTOSCIO (8-16 MHz) Clock modes with all VCAP pins disabled
		—	50	—	μA	—	All VCAP pins disabled
		—	30	—	μA	—	VCAP enabled on RA0, RA5 or RA6
		—	5	—	μA	—	LP Clock mode and Sleep (requires FVR and BOR to be disabled)
D010		—	7.0	12	μA	1.8	FOSC = 32 kHz
		—	9.0	14	μA	3.0	LP Oscillator mode (Note 4) , -40°C ≤ TA ≤ +85°C
D010		—	11	20	μA	1.8	FOSC = 32 kHz
		—	14	22	μA	3.0	LP Oscillator mode (Note 4) , -40°C ≤ TA ≤ +85°C
		—	15	24	μA	5.0	
D011		—	7.0	12	μA	1.8	FOSC = 32 kHz
		—	9.0	18	μA	3.0	LP Oscillator mode -40°C ≤ TA ≤ +125°C
D011		—	11	21	μA	1.8	FOSC = 32 kHz
		—	14	25	μA	3.0	LP Oscillator mode (Note 4) -40°C ≤ TA ≤ +125°C
		—	15	27	μA	5.0	
D011		—	110	150	μA	1.8	FOSC = 1 MHz
		—	150	215	μA	3.0	XT Oscillator mode
D011		—	120	175	μA	1.8	FOSC = 1 MHz
		—	180	250	μA	3.0	XT Oscillator mode (Note 5)
		—	240	300	μA	5.0	
D012		—	230	300	μA	1.8	FOSC = 4 MHz
		—	400	600	μA	3.0	XT Oscillator mode
D012		—	250	350	μA	1.8	FOSC = 4 MHz
		—	420	650	μA	3.0	XT Oscillator mode (Note 5)
		—	500	750	μA	5.0	
D013		—	125	180	μA	1.8	FOSC = 1 MHz
		—	230	270	μA	3.0	EC Oscillator mode
D013		—	150	205	μA	1.8	FOSC = 1 MHz
		—	225	320	μA	3.0	EC Oscillator mode (Note 5)
		—	250	410	μA	5.0	

- Note 1:** The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.
- Note 2:** The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
- Note 3:** For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.
- Note 4:** FVR and BOR are disabled.
- Note 5:** 0.1 μF capacitor on VCAP (RA0).

PIC16(L)F722/3/4/6/7

FIGURE 24-33: PIC16F722/3/4/6/7 BOR I_{PD} vs. V_{DD}, V_{CAP} = 0.1 μF

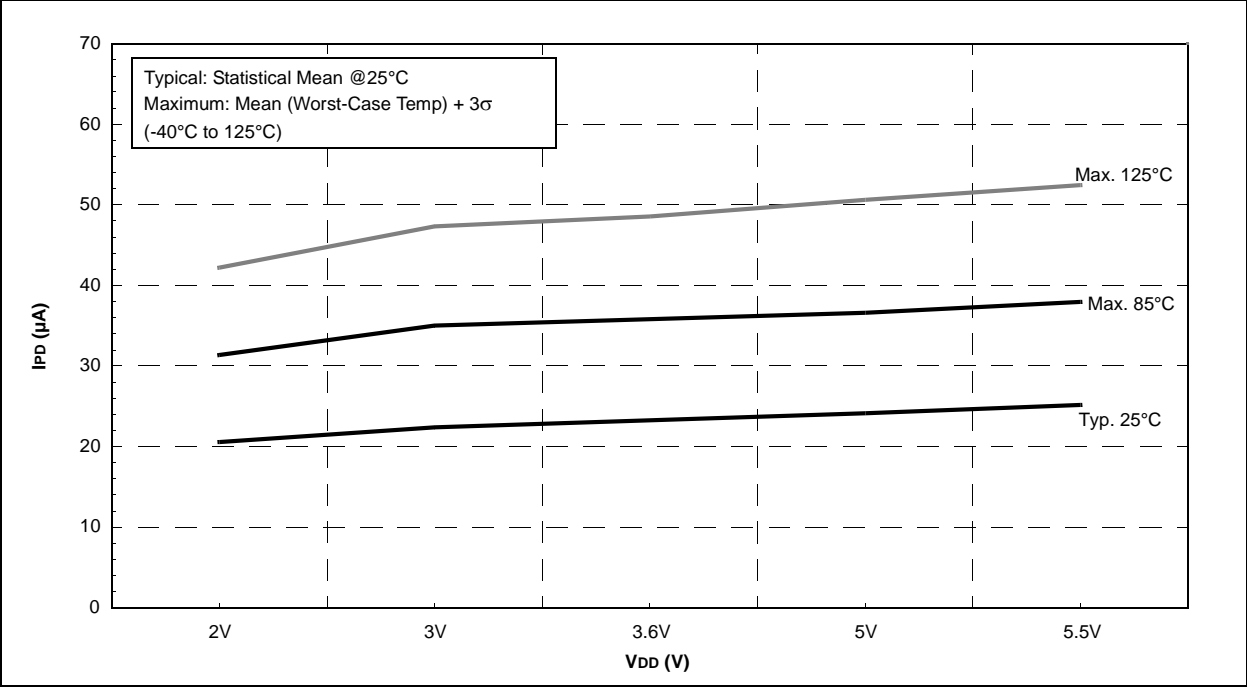
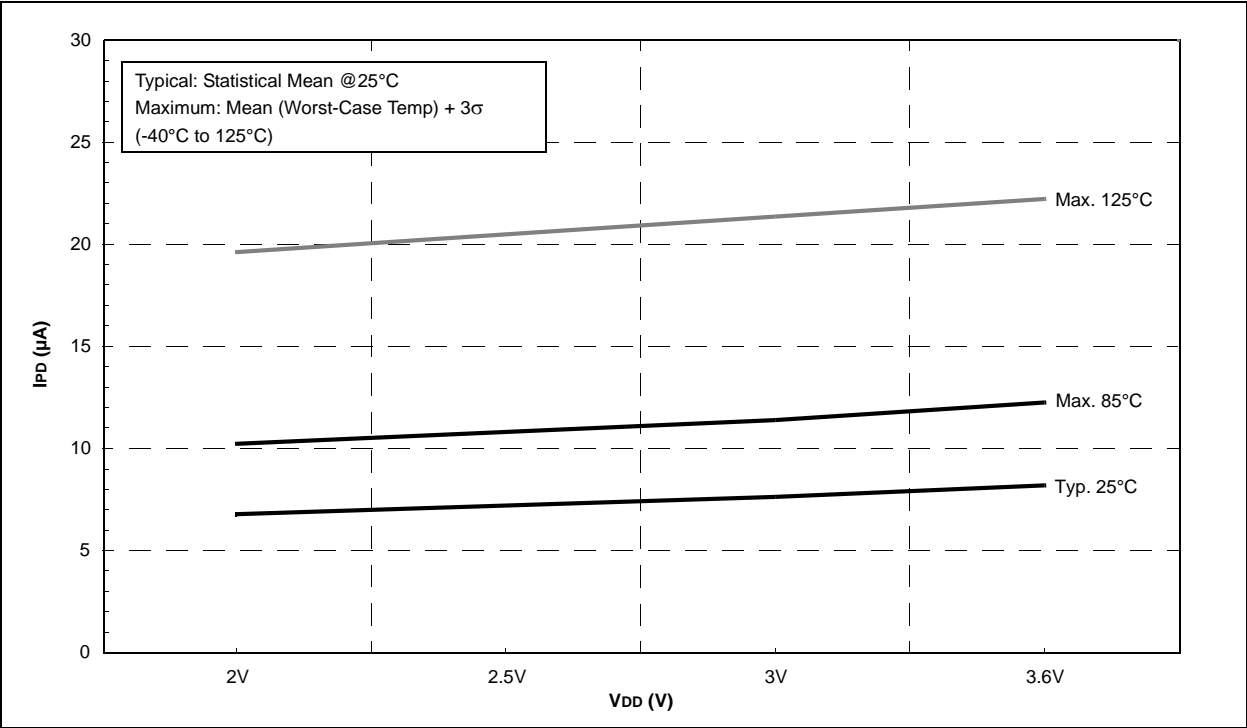


FIGURE 24-34: PIC16LF722/3/4/6/7 BOR I_{PD} vs. V_{DD}



PIC16(L)F722/3/4/6/7

FIGURE 24-57: Vol vs. IoL OVER TEMPERATURE, VDD = 1.8V

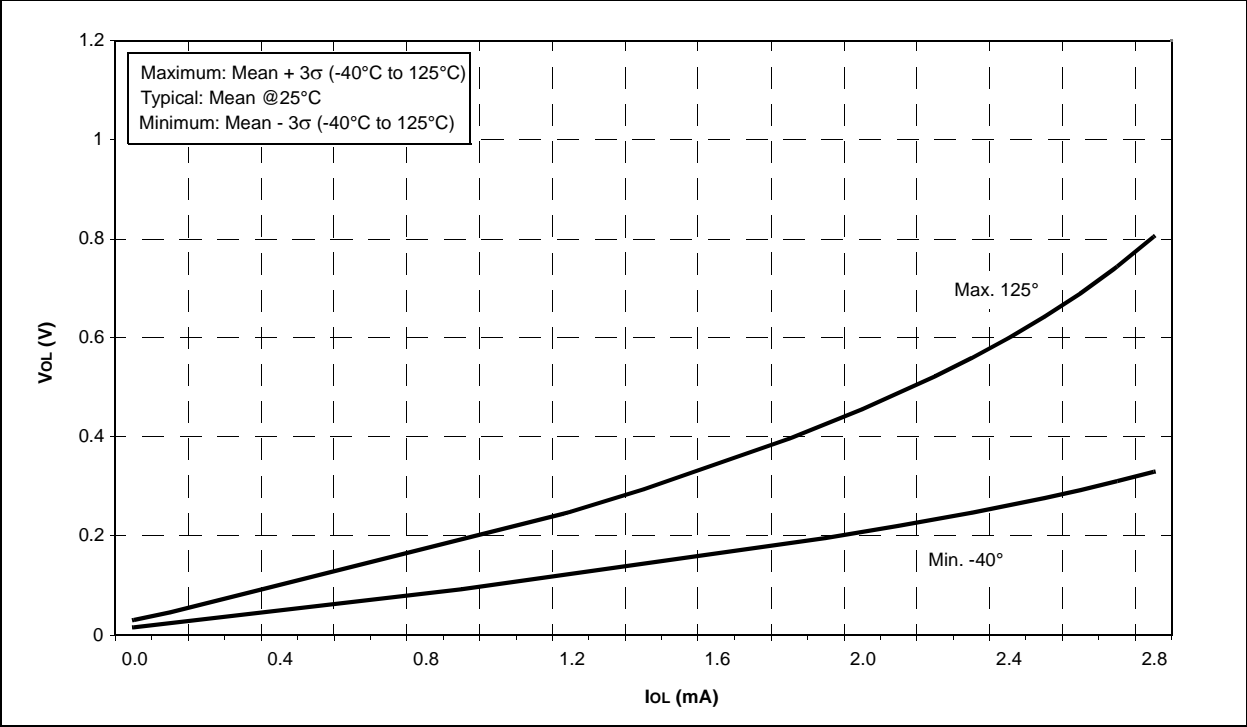


FIGURE 24-58: PIC16F722/3/4/6/7 PWRT PERIOD

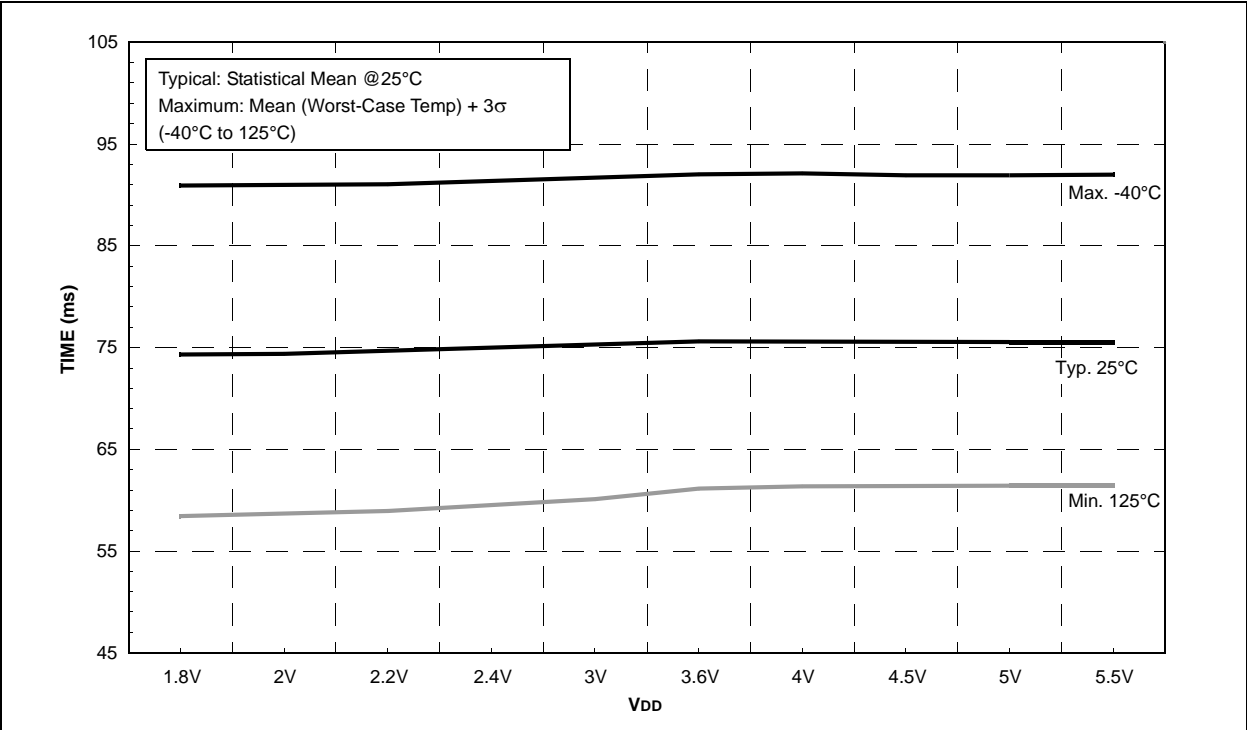


FIGURE 24-59: PIC16F722/3/4/6/7 WDT TIME-OUT PERIOD

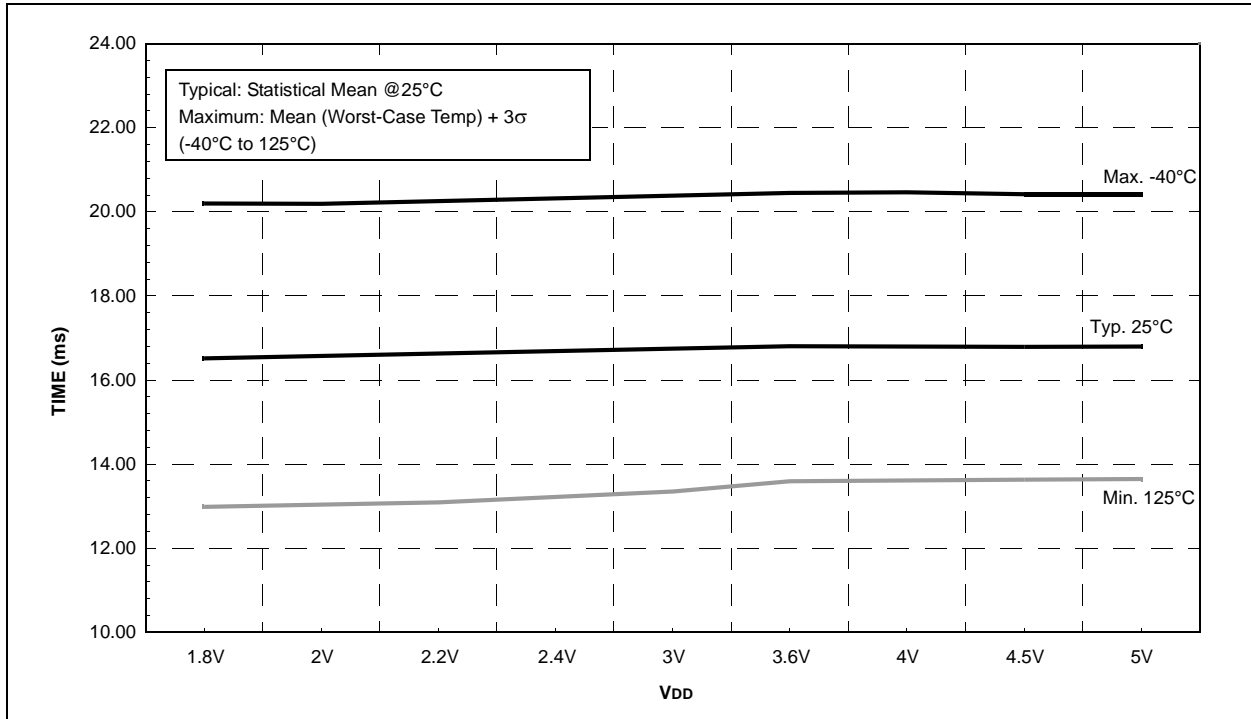
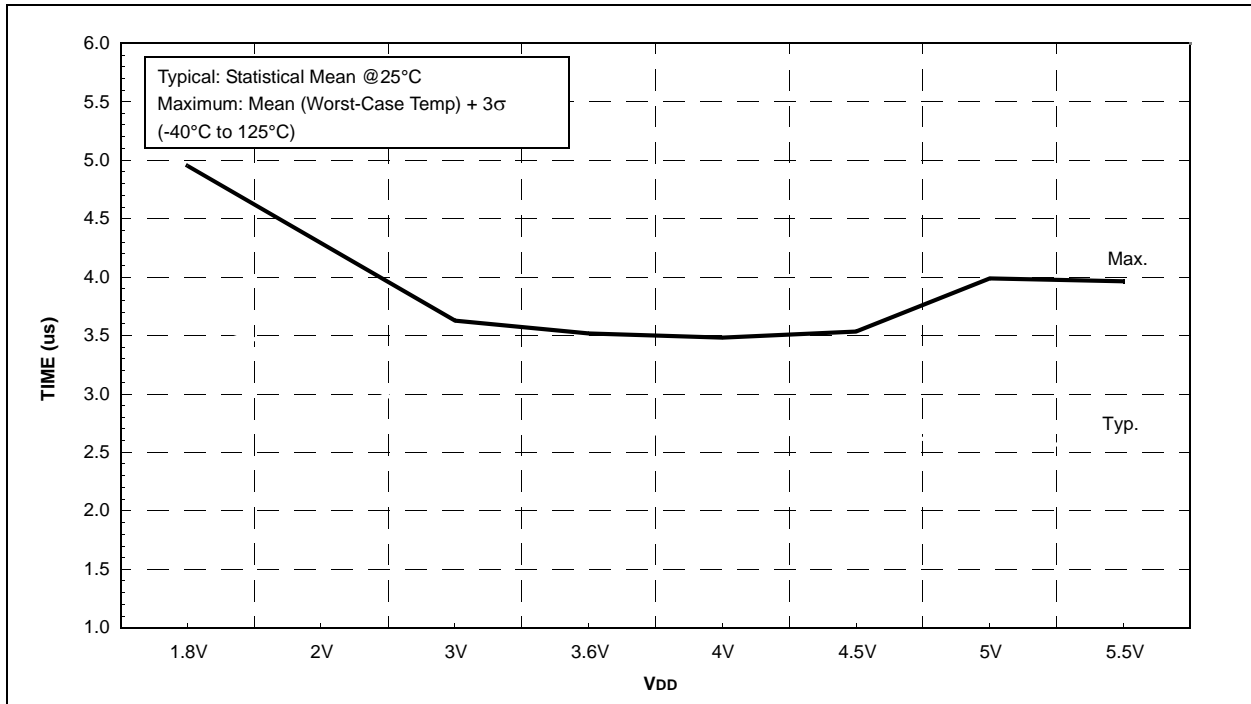


FIGURE 24-60: PIC16F722/3/4/6/7 HFINTOSC WAKE-UP FROM SLEEP START-UP TIME



PIC16(L)F722/3/4/6/7

FIGURE 24-61: PIC16F722/3/4/6/7 A/D INTERNAL RC OSCILLATOR PERIOD

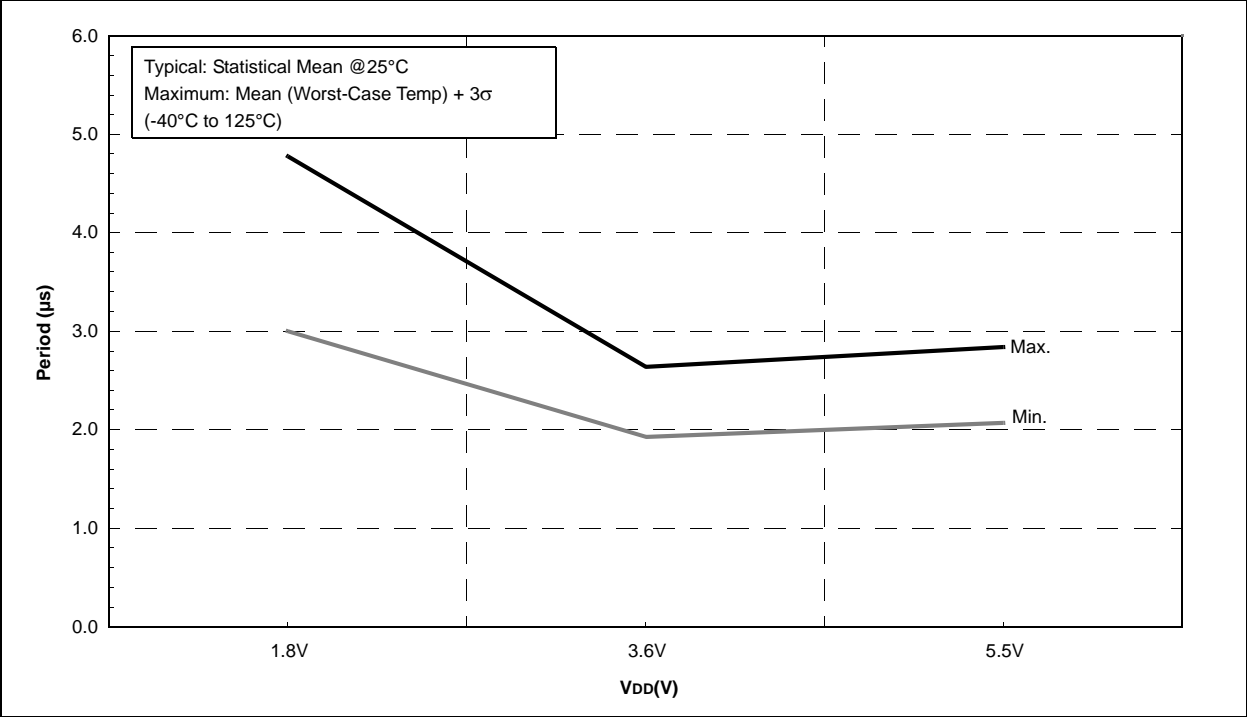
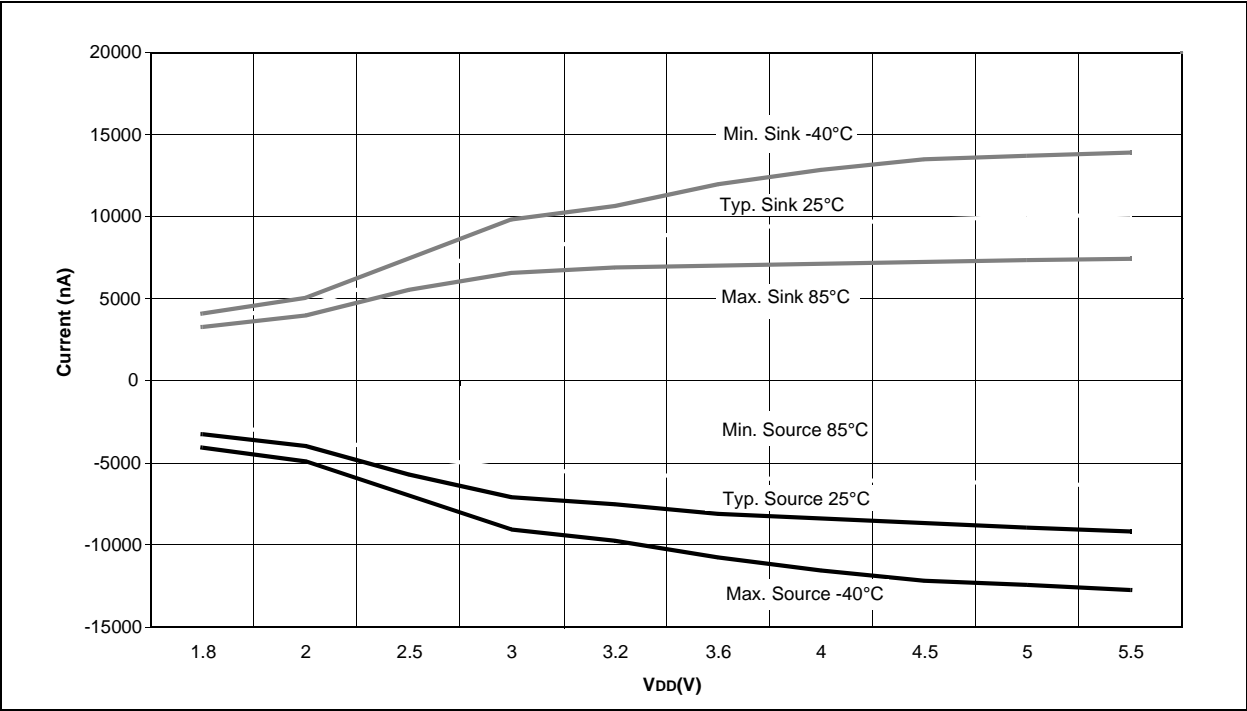
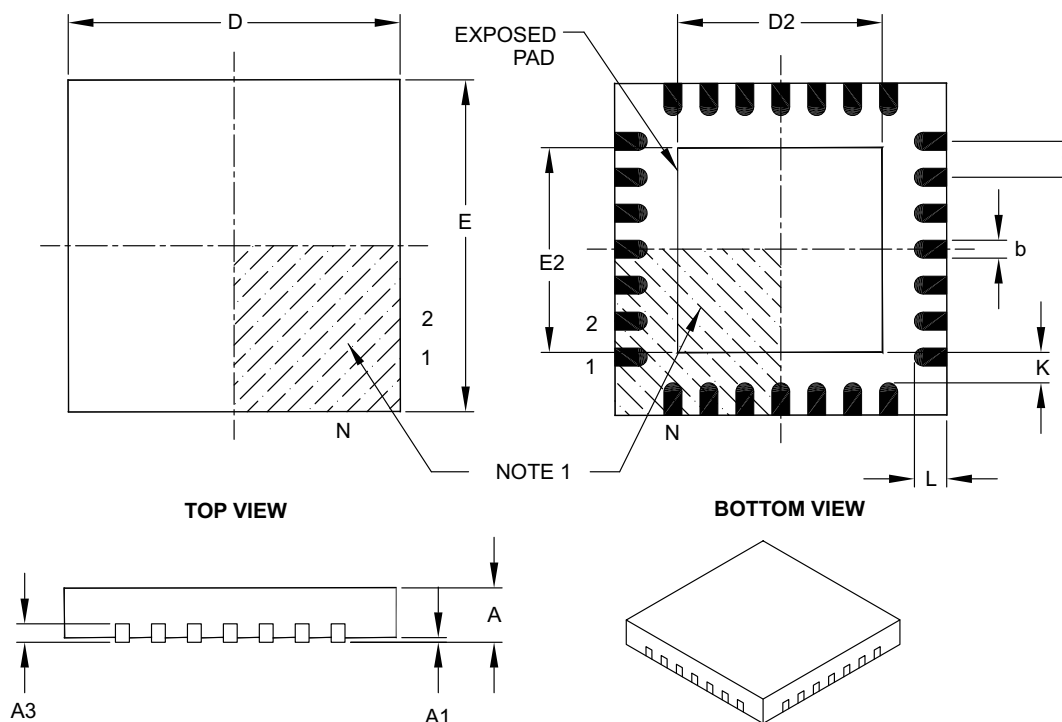


FIGURE 24-62: PIC16F722/3/4/6/7 CAP SENSE OUTPUT CURRENT, POWER MODE = HIGH



28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D	6.00 BSC		
Exposed Pad Length	D2	3.65	3.70	4.20
Contact Width	b	0.23	0.30	0.35
Contact Length	L	0.50	0.55	0.70
Contact-to-Exposed Pad	K	0.20	—	—

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B